

**BIR-HO033A-TRB** 

#### Features:

- 1. Lens Appearance: Water Clear.
- 2. 3.2x1.6x1.4mm (1206) standard package.
- 3. Suitable for all SMT assembly methods.
- 4. Compatible with infrared and vapor phase reflow solder process.
- 5. Compatible with automatic placement equipment.
- This product doesn't contain restriction Substance, comply ROHS standard.

#### Applications:

- 1. Remote Control.
- 2. Smoke Detector
- 3. Phtoto Detector
- 4. Automatic Control System

# Package Dimensions: Cathode Mark 3.2(.125)±0.2 LED die R0.4(.015) Cathode R0.2(.008) MAX. R0.1(.004) 0.50(.020) For reflow soldering 1.5(.059) 2.0(.079) 1.5(.059) 1.6(.063)

#### NOTES:

1.All dimensions are in millimeters (inches).

-0.75(.029)

2. Tolerance is ±0.10mm (0.004") unless otherwise specified.

0.75(.029)

- 3. Specifications are subject to change without notice.
- 4.Lead Spacing is measured where the leads emerge from the package.

#### ■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	/分石10尺/\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	mW
Forward Current		50	mA
Peak Forward Current *1	I <sub>FP</sub>	500	mA
Reverse Volage	Reverse Volage		V
Operating Temperature Topr		-40℃~85℃	-
Storage Temperature Tstg		-40℃~85℃	-
Soldering Temperature Tsol		See Page 6	-

\*1 Pulse With = 10us, 1%Duty Cycle

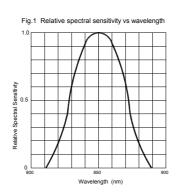


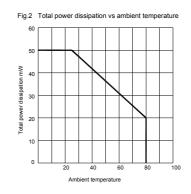
**BIR-HO033A-TRB** 

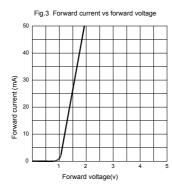
#### Electrical and optical characteristics(Ta=25℃)

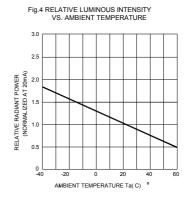
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Radiant Intensity	le	I <sub>F</sub> =50mA	3.8	8	-	mw/sr
Forward Voltage	$V_{F}$	I <sub>F</sub> =50mA	-	1.3	1.8	V
Peak Wave Length	λр	I <sub>F</sub> =20mA	-	850	-	nm
Spectral Line Half-width	Δλ	I <sub>F</sub> =20mA	-	50	-	nm
Rise/Fall Time	Tr	Ifp=20mA PW=10uS DC=1%	-	500	-	ns
	Tf		-	200	-	115
Viewing Angle	2θ <sub>1/2</sub>	I <sub>F</sub> =20mA	-	70	-	deg

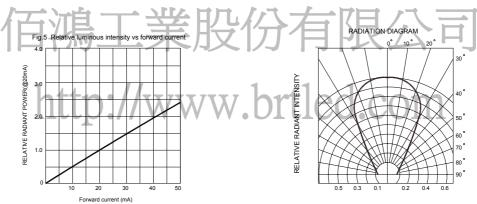
#### Typical Electro-Optical Characteristics Curves







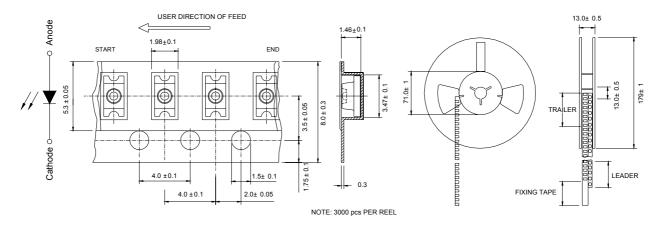




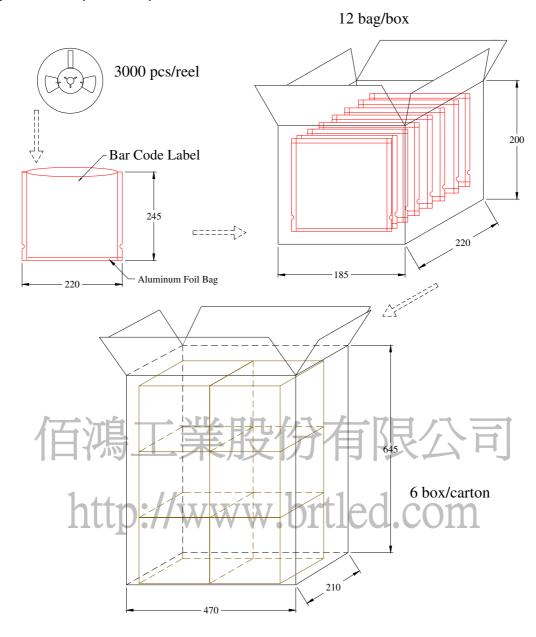


**BIR-HO033A-TRB** 

#### Tapping and packaging specifications(Units: mm)



#### ●Package Method:(unit:mm)Vacuum





**BIR-HO033A-TRB** 

#### Bin Limits

Intensity Bin Limits (At50mA)

BIN CODE	Min. (mcd)	Max. (mcd)
8	3.60	5.05
9	5.05	7.07
10	7.07	9.90
11	9.90	13.81

Tolerance for each Bin limit is  $\pm 15\%$ .

● BIN: x

Intensity BIN CODE

# 佰鴻工業股份有限公司 http://www.brtled.com



**BIR-HO033A-TRB** 

#### Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
Endurance Test	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS C 7021 :B-1	Connect with a power If=50mA Ta=Under room temperature Test time=1,000hrs	0/20
	High Temperature High Humidity Storage	MIL-STD-202:103B JIS C 7021 :B-11	Ta=+65°C±5°C RH=90%-95% Test time=240hrs	0/20
	High Temperature Storage	MIL-STD-883:1008 JIS C 7021 :B-10	High Ta=+85°C±5°C Test time=1,000hrs	0/20
	Low Temperature Storage	JIS-C-7021 :B-12	Low Ta=- $40^{\circ}$ C $\pm 5^{\circ}$ C Test time=1,000hrs	0/20
	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS C 7021 :A-4	$-40^{\circ}$ C ~ $+25^{\circ}$ C ~ $+85^{\circ}$ C ~ $+25^{\circ}$ C 60min 20min 60min 20min Test Time=5cycle	0/20
Environmental Test	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	-40°C±5°C ~ +85°C±5°C 20min 20min Test Time=10cycle	0/20
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS C 7021 :A-1	Preheating: $140^{\circ}\text{C} \cdot 160^{\circ}\text{C}$ , within 2 minutes. Operation heating: $260^{\circ}\text{C}$ (Max.), within 10seconds. (Max.)	0/20

#### Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Collector Dark Current	$I_d$	$V_{CE}=20V, H=1.0 \text{ mW/cm}^2$	Over Ux2
Collector Light Current	$I_{SC}$	$V_{CE} = 5V, H = 1.0 \text{ mW/cm}^2$	Below SX0.5

Note: 1.U means the upper limit of specified characteristics. S means initial value.

2.Measurment shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.



**BIR-HO033A-TRB** 

#### Soldering :

1. Manual Of Soldering

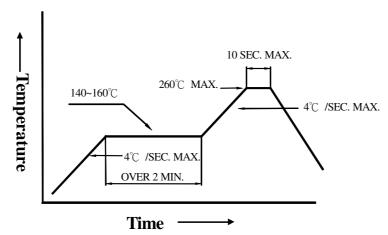
The temperature of the iron tip should not be higher than  $300^{\circ}$ C (572°F) and Soldering within 3 seconds per solder-land is to be observed.

2. Reflow Soldering

Preheating: 140°C ~160°C ±5°C, within 2 minutes.

Operation heating: 260°C (Max.) within 10 seconds.(Max)

Gradual Cooling (Avoid quenching).

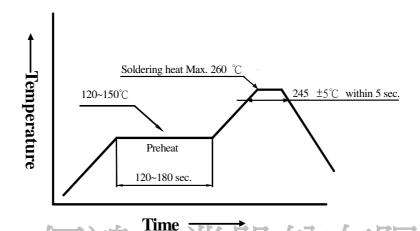


3. DIP soldering (Wave Soldering):

Preheating:  $120^{\circ}\text{C} \sim 150^{\circ}\text{C}$ , within  $120 \sim 180$  sec.

Operation heating :  $245^{\circ}C \pm 5^{\circ}C$  within 5 sec.260°C (Max)

Gradual Cooling (Avoid quenching).



#### Handling :

Care must be taken not to cause to the epoxy resin portion of BRIGHT LEDs while it is exposed to high temperature.

Care must be taken not rub the epoxy resin portion of BRIGHT LEDs with hard or sharp article such as the sand blast and the metal hook.



**BIR-HO033A-TRB** 

#### Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the BRIGHT LEDs within the rated figures. Also, caution should be taken not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as be subjected to reverse voltage when turning off the BRIGHT LEDs.

#### Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature :  $5^{\circ}$ C  $30^{\circ}$ C ( $41^{\circ}$ F)Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
- a. Completed within 168 hours.
- b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if: (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions: 48 hours at  $60^{\circ}\text{C} \pm 3^{\circ}\text{C}$ .

#### Package and Label of Products:

- (1) Package: Products are packed in one bag of 3000 pcs (one taping reel) and a label is attached on each bag.
- (2) Label:

